

CLAIM AMENDMENTS:

Claim 1 (Currently Amended): A semiconductor ~~device~~device, ~~comprising~~
comprising:

a pellet having a ground ~~electrode~~electrode; ~~and~~
an outside signal terminal connected to the pellet, so as to receive a signal
which is likely to include noise; wherein
at least a half of a periphery of said outside signal terminal is surrounded
with a ground terminal that is connected to said ground electrode ~~in at least a half~~
~~periphery~~.

Claim 2 (Currently Amended): A semiconductor device according to Claim
1, wherein said outside signal terminal ~~can receive~~receives the signal by an
antenna mounted on the apparatus where the semiconductor device is installed.

Claim 3 (Currently Amended): A semiconductor device according to Claim
1, wherein said outside signal terminal ~~can receive~~receives an operating clock
from the apparatus where the semiconductor device is installed.

Claim 4 (Currently Amended): A semiconductor device according to Claim
1, wherein said outside signal terminal ~~can receive~~receives an electricity source
from the apparatus where the semiconductor device is installed.

Claim 5 (Currently Amended): A semiconductor device according to Claim 1, wherein said ground terminal ~~can surround~~ surrounds only half of the periphery of said outside signal terminal.

Claim 6 (Currently Amended): A semiconductor device according to Claim 1, wherein said semiconductor device ~~can be~~ is provided with a fixing reinforcement terminal to reinforce the fixing of the semiconductor device to the apparatus installing it.

Claim 7 (Currently Amended): A semiconductor device according to Claim 1, wherein said semiconductor device is provided with plural terminals for electrical ~~connection; and,~~ connection, each terminal is projecting at ~~the~~ a base of ~~the~~ the semiconductor device to connect with a socket.

Claim 8 (Currently Amended): A semiconductor device according to Claim 1, wherein said semiconductor device is provided with a pair of semiconductor pellets; wherein at the base of one of the semiconductor pellets, the other semiconductor pellet is located; ~~and,~~ and wherein electrodes of the other semiconductor pellet ~~can be~~ are connected with the plural terminals electrically.

Claim 9 (Currently Amended): A semiconductor device according to Claim 48, wherein ~~a~~ the pair of semiconductor pellets ~~mentioned above~~ are fixed with each other at confronting faces with conductive paste; ~~and, this conductive paste can be paste that is~~ electrically connected with said ground terminal.

Claims 10-17 (Canceled).